

Listing of Claims

This list of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A circuit, comprising:
 electronic component having an enclosure that protects the electronic component;
 structure that surrounds the enclosure and that reduces a thermal drift of the
 electronic component by increasing a thermal mass of the electronic component,
 wherein the electronic component controls a frequency used by the circuit.
2. (Cancelled)
3. (Previously presented) The circuit of claim 1, wherein the structure comprises a metal case around the enclosure.
4. (Previously Presented) The circuit of claim 1, wherein the structure comprises a ceramic case around the enclosure.
5. (Cancelled)
6. (Previously Presented) The circuit of claim 1, further comprising an insulator that encases the structure.
- Claims 7-11. (Cancelled)
12. (Original) The circuit of claim 1, wherein the circuit is an oscillator circuit.
13. (Original) The circuit of claim 1, wherein the circuit is a clock circuit.

14. (Previously Presented) The circuit of claim 13, further comprising:

means for communication via a network;

means for synchronizing a local time value in the clock circuit in response to a set of messages transferred via the network.

15. (Previously Presented) A distributed system having a set of nodes, each node comprising:

local clock including a crystal component having an enclosure that protects the crystal component;

structure that surrounds the enclosure and that reduces a thermal drift of the crystal component by increasing a thermal mass of the crystal component.

16. (Cancelled)

17. (Previously Presented) The distributed system of claim 15, wherein the structure comprises a metal case around the enclosure.

18. (Previously Presented) The distributed system of claim 15, wherein the structure comprises a ceramic case around the enclosure.

19. (Cancelled)

20. (Previously Presented) The distributed system of claim 15, further comprising an insulator that encases the structure.

21. (Withdrawn) A circuit, comprising:

electronic component;

structure for thermally isolating the electronic component from a set of other components of the circuit.

22. (Withdrawn) The circuit of claim 21, wherein the structure comprises a circuit board that holds the electronic component and that is separated from a circuit board that holds the other components of the circuit.

23. (Withdrawn) The circuit of claim 22, wherein the structure further comprises a material that increases a thermal mass of the electronic component.

24. (Withdrawn) The circuit of claim 22, wherein the structure further comprises an insulator over the electronic component.

25. (Withdrawn) The circuit of claim 22, wherein the structure further comprises a material that increases a thermal mass of the electronic component and an insulator that encases the electronic component and the material.

26. (Withdrawn) The circuit of claim 21, wherein the structure comprises a gap in a ground plane of a circuit board that holds the electronic component and the other components and which reduces a heat conduction path between the ground plane and the electronic component.

27. (New) A circuit as in claim 1, wherein the electronic component is a crystal having a vibration frequency.